

WEST

## Freeform Search

**Database:**

US Patents Full-Text Database  
 US Pre-Grant Publication Full-Text Database  
 JPO Abstracts Database  
 EPO Abstracts Database  
 Derwent World Patents Index  
 IBM Technical Disclosure Bulletins

**Term:**

(decapsulat\$3 near5 fluid) same (integrated  
 circuit package or "IC")

**Display:**

25

**Documents in Display Format:**

CIT

**Starting with Number**

1

**Generate:**  Hit List  Hit Count  Image**Search****Clear****Help****Logout****Interrupt****Main Menu****Show S Numbers****Edit S Numbers****Preferences**

## Search History

Today's Date: 9/9/2001

| <u>DB Name</u>                | <u>Query</u>   | <u>Hit Count</u> | <u>Set Name</u> |
|-------------------------------|--|------------------|-----------------|
| USPT,PGPB,JPAB,EPAB,DWPI,TDBD | (decapsulat\$3 near5 fluid) same (integrated circuit package or "IC")                    | 2                | <u>L5</u>       |
| USPT,PGPB,JPAB,EPAB,DWPI,TDBD | 11 and (circuit board)   | 1                | <u>L4</u>       |
| USPT,PGPB,JPAB,EPAB,DWPI,TDBD | l2 not 11  | 6                | <u>L3</u>       |
| USPT,PGPB,JPAB,EPAB,DWPI,TDBD | (decapsulat\$3 or remov\$3 near3 encapsulat%4) same (integrated circuit package or "IC") | 17               | <u>L2</u>       |
| USPT,PGPB                     | (decapsulat\$3 or remov\$3 near3 encapsulat%4) same (integrated circuit package or "IC") | 11               | <u>L1</u>       |